



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS5482SF		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001120934						
<b>Package</b>		PG-DSO-36-43		<b>Weight*</b>		634.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.928	2.04	2.04	20367	20367
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.01		96	
	non noble metal	zinc	7440-66-6	0.244	0.04		384	
wire	non noble metal	iron	7439-89-6	4.881	0.77		7690	
	non noble metal	copper	7440-50-8	198.190	31.22	32.04	312231	320401
	noble metal	gold	7440-57-5	0.883	0.14		1391	
encapsulation	non noble metal	aluminium	7429-90-5	2.770	0.44	0.58	4363	5754
	organic material	carbon black	1333-86-4	0.807	0.13		1271	
	plastics	epoxy resin	-	57.685	9.09		90877	
leadfinish	inorganic material	silicondioxide	60676-86-0	344.897	54.32	63.54	543355	635503
	non noble metal	tin	7440-31-5	5.006	0.79	0.79	7887	7887
plating	noble metal	silver	7440-22-4	3.335	0.53	0.53	5254	5254
glue	plastics	epoxy resin	-	0.537	0.08		846	
	noble metal	silver	7440-22-4	2.531	0.40	0.48	3988	4834
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

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